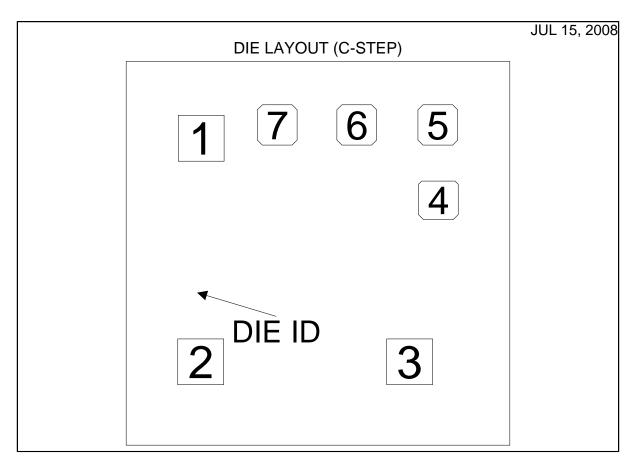


LM4040AI4.1 MWC PRECISION MICROPOWER SHUNT VOLTAGE REFERENCE



DIE/WAFER CHARACTERISTICS

| Fabrication Attributes | | General Die Information | | | | |
|--|-----------------------|-------------------------|-------------------|--|--|--|
| Physical Die | LM4040C-4V | Bond Pad Opening | 91.00µm x 91.00µm | | | |
| Identification | | Size (min) | | | | |
| Die Step | С | Bond Pad Metalization | AL 0.5%CU | | | |
| Physical Attributes | | Passivation | PECVDOX NITRIDE | | | |
| Wafer Diameter | 150mm | Back Side Metal | BAREBACK | | | |
| Die Size (Drawn) | 762.000µm x 762.000µm | Back Side Connection | Floating | | | |
| | 30.0mils x 30.0mils | | | | | |
| Thickness | 216µm Nominal | | | | | |
| Min Pitch | 444µm | | | | | |
| Note: All values are rounded to the pogreet migran | | | | | | |

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

!!!! NOTICE !!!

Application of encapsulants or glob top material on this device is not recommended.

"A" tolerance die is very sensitive to the packaging. Compressive forces of encapsulants or glob top will affect the tolerance spread in both plus and minus.



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| (Referenced t | Die Bond Pad Coordi o die center, coordinates in | | · | U. = Not U | sed | |
|---------------|---|--------------------|------|------------|----------|----|
| Signal Name | Pad Number | er X/Y Coordinates | | Р | Pad Size | |
| J | | Χ | Υ | Χ | | Υ |
| + | 1 | -232 | 228 | 91 | Х | 91 |
| - | 2 | -233 | -215 | 91 | Х | 91 |
| NC | 3 | 182 | -215 | 91 | Х | 91 |
| NC | 4 | 239 | 105 | 79 | Х | 76 |
| NC | 5 | 238 | 255 | 79 | х | 80 |
| NC | 6 | 77 | 255 | 79 | х | 80 |
| NC | 7 | -81 | 255 | 79 | Х | 80 |



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| Notes |
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